



Material Content Data Sheet



Sales Product Name		BTS50010-1TAD		Issued		9. January 2019		
MA#		MA004091352						
Package		PG-TO263-7-10		Weight*		1558.46 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	12.330	0.79	0.79	7912	7912
chip_2	inorganic material	silicon	7440-21-3	1.848	0.12	0.12	1186	1186
leadframe	inorganic material	phosphorus	7723-14-0	0.247	0.02		159	
	non noble metal	iron	7439-89-6	0.823	0.05		528	
	non noble metal	copper	7440-50-8	822.375	52.77	52.84	527685	528372
	non noble metal	aluminium	7429-90-5	15.627	1.00	1.00	10027	10027
wire	organic material	carbon black	1333-86-4	8.270	0.53		5306	
	plastics	epoxy resin	-	90.965	5.84		58369	
encapsulation	inorganic material	silicondioxide	60676-86-0	452.069	29.01	35.38	290074	353749
	non noble metal	tin	7440-31-5	12.163	0.78	0.78	7804	7804
plating	inorganic material	phosphorus	7723-14-0	0.007	0.00		5	
	non noble metal	nickel	7440-02-0	2.941	0.19	0.19	1887	1892
solder	non noble metal	tin	7440-31-5	0.157	0.01		101	
	noble metal	silver	7440-22-4	0.196	0.01		126	
	non noble metal	lead	7439-92-1	7.483	0.48	0.50	4801	5028
	plastics	Polyimide	26023-21-2	0.198	0.01	0.01	127	127
glue	inorganic material	phosphorus	7723-14-0	0.039	0.00		25	
	non noble metal	iron	7439-89-6	0.131	0.01		84	
heatspreader	non noble metal	iron	7439-89-6	0.131	0.01		84	
	non noble metal	copper	7440-50-8	130.589	8.38	8.39	83794	83903
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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